Innovative Sensor Technology
physical. chemical. biological.

P0K1.0805.1FC.B

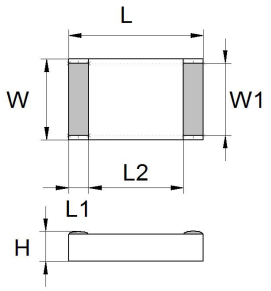
FlipChip platinum sensor

For the automatic assembling on PCB by soldering or bonding

Benefits & Characteristics

- Excellent long-term stability
- Low self-heating
- Fast response time
- Minimum space consumption on PCB
- Optimal price-performance ratio

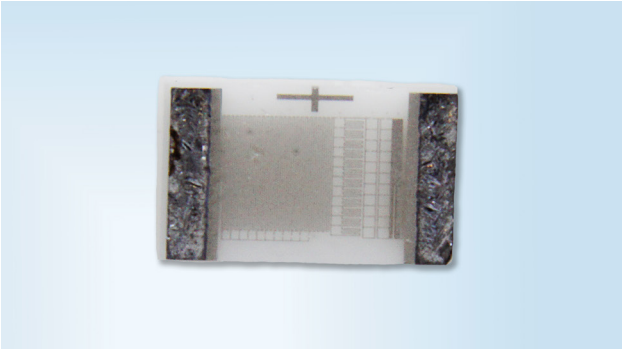
Illustration[1)]



Technical Data

Operating temperature range:	-50 °C to +150 °C
Nominal resistance:	100 Ω at 0 °C
Characteristics curve:	3850 ppm/K
Long-term stability:	< 0.04 % at 1000 h at 130 °C
Tolerance class (dependent on temperature range):	IEC 60751 F0.3 B (IST AG reference)
Connection:	tin-coated, LMP lead-free, 96.5Sn/3Ag/0.5Cu) (reflow soldering)
Dimensions:	1.9 / 0.25 / 1.4 x 1.15 / 1.1 x 0.45
Tolerance:	±0.2 mm (H ±0.15)
Solderability:	235 °C ≤ 8 s (DIN IEC 68 T2-20, Ta Meth. 1)
Resistance to soldering heat:[1)] 1) The soldering process can influence accuracy	260 °C 10 s (DIN IEC 68 T2-20, Ta Meth. 1A)
Recommended applied current:[2)] 2) Self-heating must be considered	1 mA at 100 Ω
Packaging:	< 100 pcs in trays

Product Photo



Order Information

Description:	Item number:	Former main reference:
P0K1.0805.1FC.B	101146	010.02586

Additional Documents

	Document name:
Application Note:	ATP_E

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